

# **MOSFET** – N-Channel, SUPERFET® II, Easy-Drive

600 V, 10.2 A, 380 mΩ

# FCP380N60E, FCPF380N60E

#### Description

SUPERFET II MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SUPERFET II MOSFET easy-drive series offers slightly slower rise and fall times compared to the SUPERFET II MOSFET series. Noted by the "E" part number suffix, this family helps manage EMI issues and allows for easier design implementation. For faster switching in applications where switching losses must be at an absolute minimum, please consider the SUPERFET II MOSFET series.

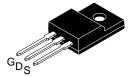
#### **Features**

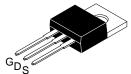
- 650 V @  $T_I = 150$ °C
- Typ.  $R_{DS(on)} = 320 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 34 \text{ nC}$ )
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 97 pF)
- 100% Avalanche Tested
- An Integrated Gate Resistor
- RoHS Compliant

## **Applications**

- LCD / LED / PDP TV Lighting
- Solar Inverter
- AC-DC Power Supply



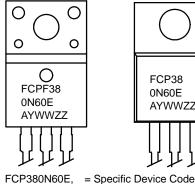


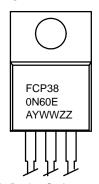


TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT

TO-220-3LD CASE 340AT

## **MARKING DIAGRAM**





FCP380N60E. FCPF380N60E

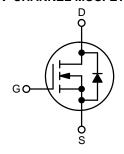
YWW

1

= Assembly Location = Date Code (Year & Week)

ZZ = Assembly Lot

### **N-CHANNEL MOSFET**



#### ORDERING INFORMATION

Part Number	Package	Shipping
FCP380N60E	TO-220	800 Units / Tube
FCPF380N60E	TO-220F	1000 Units / Tube

## **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ , unless otherwise noted)

Symbol	Parameter		FCP380N60E	FCPF380N60E	Unit
$V_{DSS}$	Drain to Source Voltage		600		V
V <sub>GSS</sub> Gate to Source Voltage – D		- DC	±20		V
		– AC (f > 1 Hz)	±30		1
Ι <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	10.2	10.2*	Α
		− Continuous (T <sub>C</sub> = 100°C)	6.4	6.4*	1
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	30.6	30.6*	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		211.6		mJ
I <sub>AR</sub>	Avalanche Current (Note 1)		2.3		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		1.06		mJ
dv/dt	MOSFET dv/dt		100		V/ns
	Peak Diode Recovery dv/dt (Note 3)		20		]
$P_{D}$	Power Dissipation	(T <sub>C</sub> = 25°C)	106	31	W
		– Derate Above 25°C	0.85	0.25	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. \*Drain current limited by maximum junction temperature.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	FCP380N60E	FCPF380N60E	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1.18	4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	62.5	

<sup>1.</sup> Repetitive rating: pulse–width limited by maximum junction temperature. 2.  $I_{AS} = 2.3 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 5.1 \text{ A}$ , di/dt  $\le 200 \text{ A/}\mu\text{s}$ ,  $V_{DD} \le \text{BV}_{DSS}$ , starting  $T_J = 25^{\circ}\text{C}$ .

## **ELECTRICAL CHARACTERISTICS** ( $T_C = 25$ °C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHAR	ACTERISTICS	•			•	
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 mA, T <sub>J</sub> = 25°C	600	_	_	V
		V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 mA, T <sub>J</sub> = 150°C	650	_	-	V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	0.67	_	V/°C
BV <sub>DS</sub>	Drain to Source Avalanche Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 A	-	700	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	_	1	μΑ
		V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C	_	0.84	_	
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	_	_	±100	nA
	CTERISTICS			L		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	_	3.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A	_	0.32	0.38	Ω
9FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 5 A	_	10	_	S
DYNAMIC (	CHARACTERISTICS			ı	1	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1330	1770	pF
C <sub>oss</sub>	Output Capacitance	1	_	945	1260	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1	_	60	90	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	25	_	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V	_	97	_	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V	_	34	45	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	(Note 4)	_	5.3	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	1	_	13	_	nC
ESR	Equivalent Series Resistance	f = 1 MHz	_	6	_	Ω
SWITCHING	CHARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 380 V, I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V,	_	17	44	ns
t <sub>r</sub>	Turn-On Rise Time	$R = 4.7 \Omega \text{ (Note 4)}$	_	9	28	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	1	_	64	138	ns
t <sub>f</sub>	Turn-Off Fall Time	1	_	10	30	ns
	URCE DIODE CHARACTERISTICS	1	1	1	1	
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		_	_	10.2	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	_	30.6	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	i e		_	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{SD} = 5 \text{ A, } dI_F/dt = 100 \text{ A/}\mu\text{s}$	_	240	_	ns
Q <sub>rr</sub>	Reverse Recovery Charge	1		3	_	μC
	, ,	trical Characteristics for the listed test con	L		I	•

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

#### TYPICAL PERFORMANCE CHARACTERISTICS

ID, Drain Current (A)

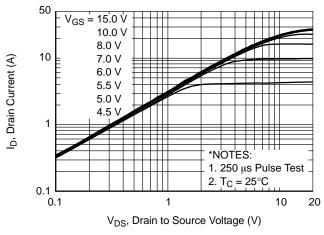


Figure 1. On-Region Characteristics

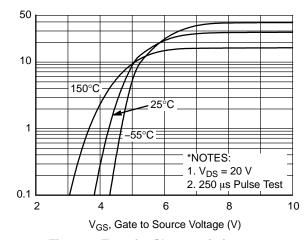


Figure 2. Transfer Characteristics

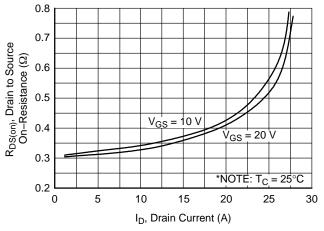


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

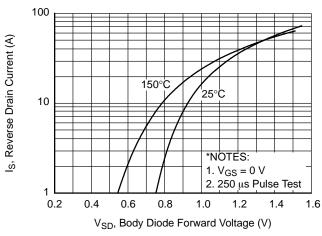


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

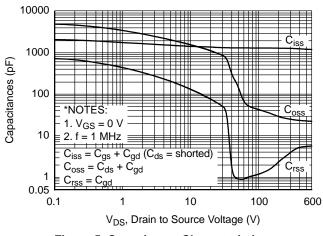


Figure 5. Capacitance Characteristics

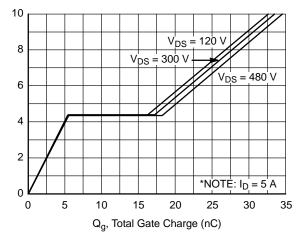


Figure 6. Gate Charge Characteristics

V<sub>GS</sub>, Gate to Source Voltage (V)

## TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

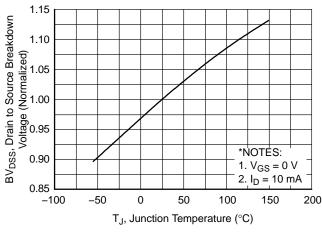


Figure 7. Breakdown Voltage Variation vs. Temperature

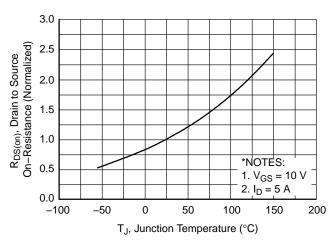


Figure 8. On–Resistance Variation vs. Temperature

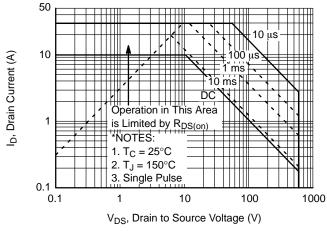


Figure 9. Maximum Safe Operating Area for FCP380N60E

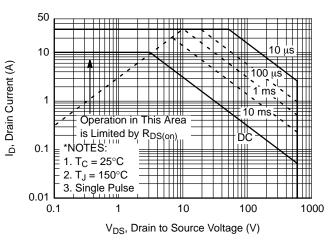


Figure 10. Maximum Safe Operating Area for FCPF380N60E

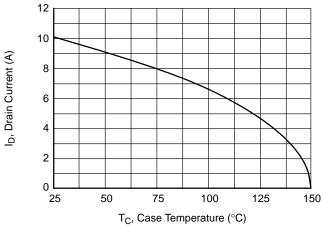


Figure 11. Maximum Drain Current vs.

Case Temperature

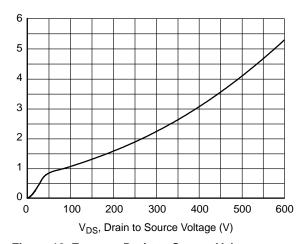


Figure 12. E<sub>OSS</sub> vs. Drain to Source Voltage

Eoss (µJ)

## TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

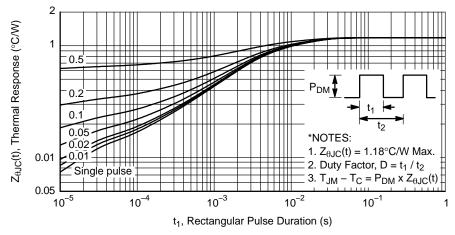


Figure 13. Transient Thermal Response Curve for FCP380N60E

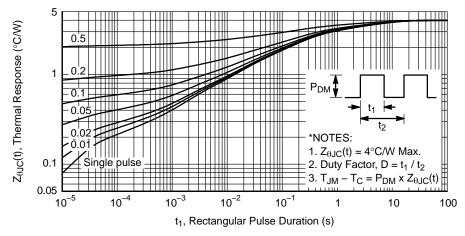


Figure 14. Transient Thermal Response Curve for FCPF380N60E

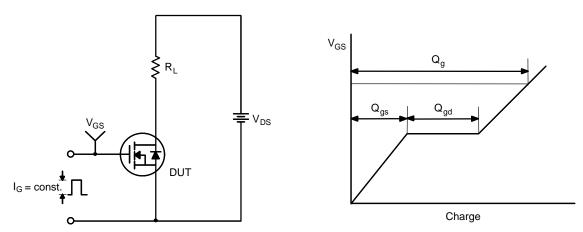


Figure 15. Gate Charge Test Circuit & Waveform

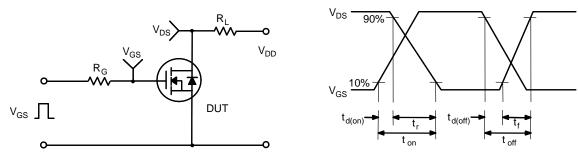


Figure 16. Resistive Switching Test Circuit & Waveforms

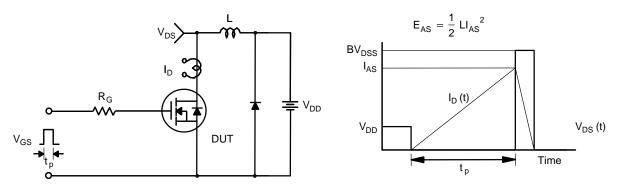
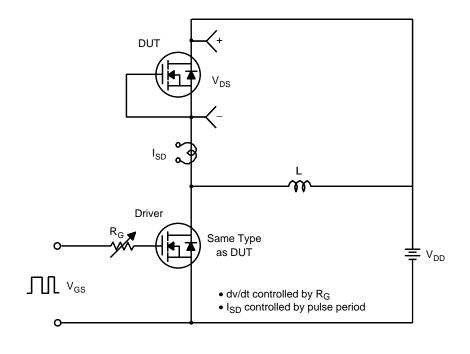


Figure 17. Unclamped Inductive Switching Test Circuit & Waveforms



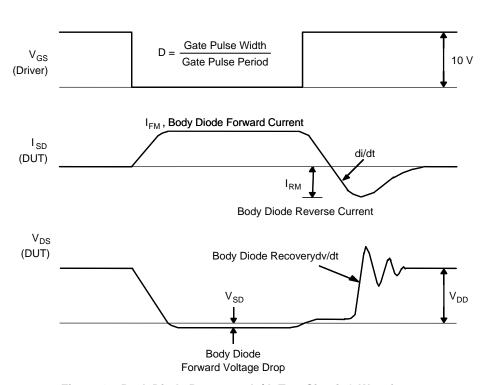
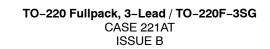
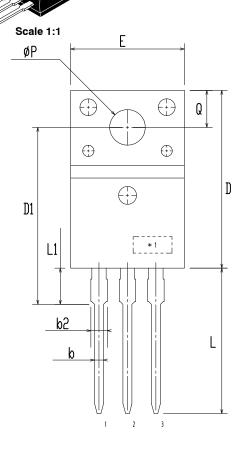


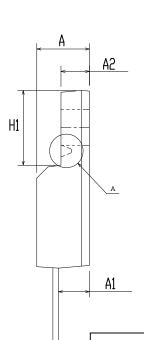
Figure 18. Peak Diode Recovery dv/dt Test Circuit & Waveforms

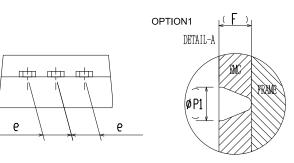
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**DATE 19 JAN 2021** 







DIM	MIL	LIMITERS	
DIM	MIN	NDM	MAX
Α	4.50	4.70	4.90
A1	2.56	2.76	2.96
A2	2.34	2.54	2.74
b	0.70	0.80	0.90
b2	*	2	1.47
C	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.60	15.80	16.00
E	9.96	10.16	10.36
е	2.34	2.54	2.74
F	~	0.84	~
H1	6.48	6.68	6.88
Ш	12.78	12.98	13.18
L1	3.03	3.23	3.43
ØΡ	2.98	3.18	3.38
Ø P1	~	1.00	~
Q	3.20	3.30	3.40

## NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

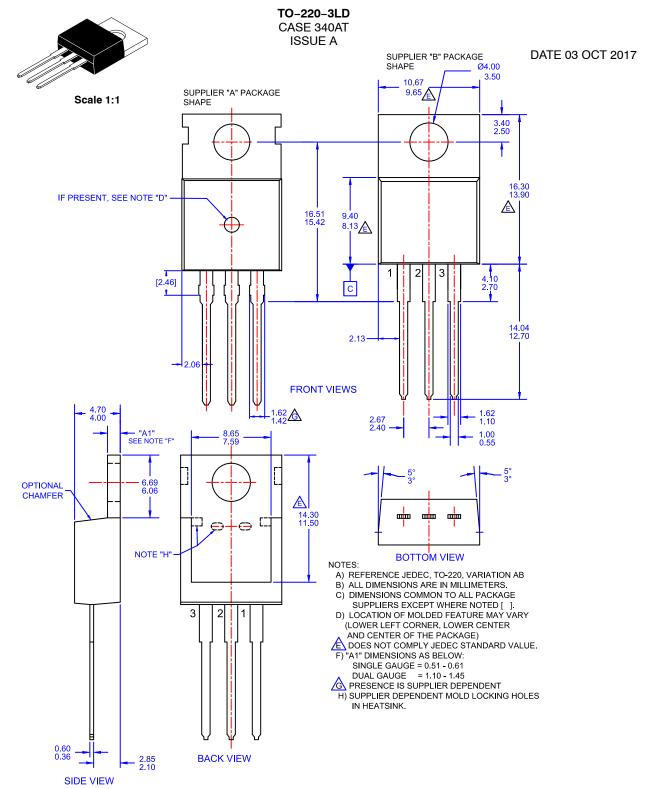
C. OPTION 1 - WITH SUPPORT PIN HOLE

OPTION 2 - NO SUPPORT PIN HOLE

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